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**Field Device Integration (FDI) –
Part 4: FDI Packages**

**Intégration des appareils de terrain (FDI) –
Partie 4: Paquetages FDI**



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Part 4: FDI Packages**

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INTERNATIONAL
ELECTROTECHNICAL
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ICS 25.040.40; 35.100

ISBN 978-2-8322-2640-7

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FIELD DEVICE INTEGRATION (FDI) –

Part 4: FDI Packages

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CDV	Report on voting
65E/347/CDV	65E/424/RVC

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FIELD DEVICE INTEGRATION (FDI) –

Part 4: FDI Packages

1 Scope

This part of IEC 62769 specifies the FDI Packages. The overall FDI architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this figure.

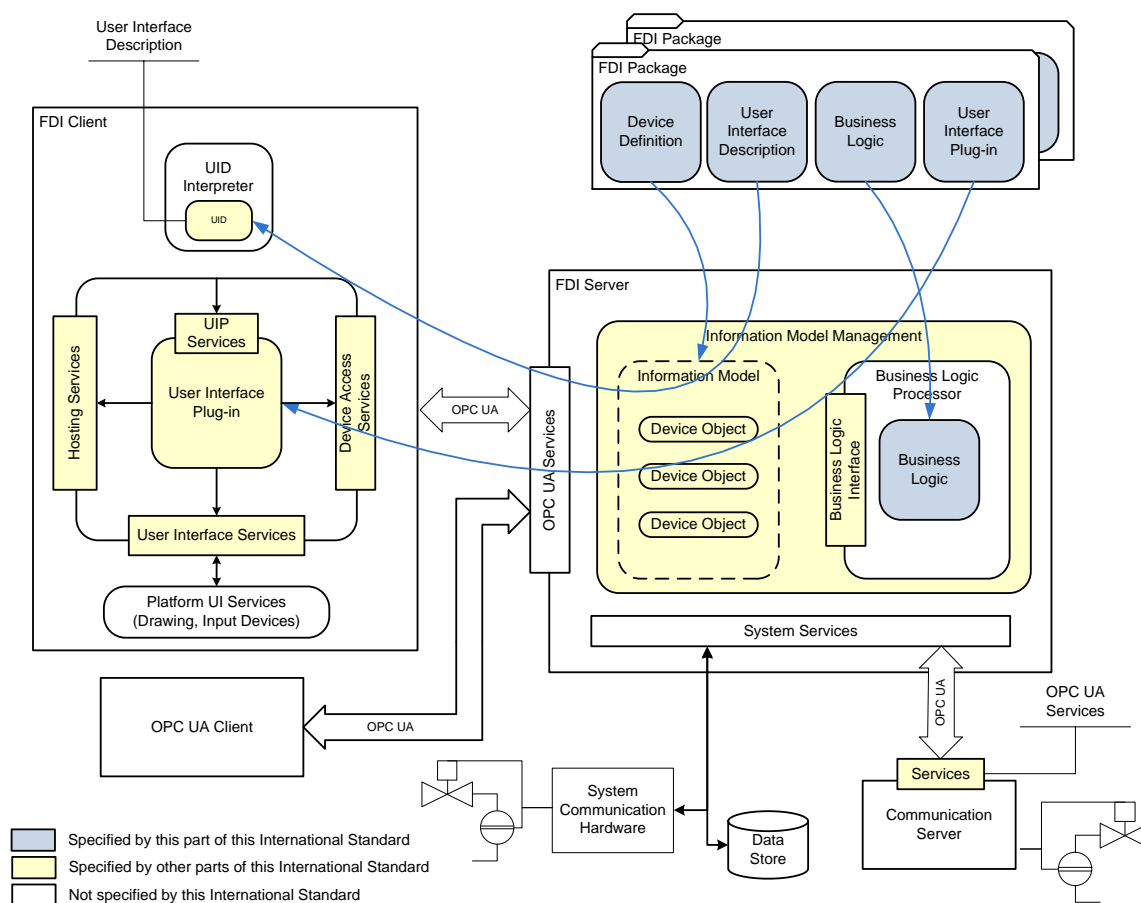


Figure 1 – FDI architecture diagram

2 Normative references

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